

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hui Chong Vince Ng</td> <td>08/16/2010</td> </tr> <tr> <td>Olivier Le Neel</td> <td>08/16/2010</td> </tr> <tr> <td>Calvin Leung</td> <td>08/16/2010</td> </tr> </tbody> </table>		Name	Execution Date	Hui Chong Vince Ng	08/16/2010	Olivier Le Neel	08/16/2010	Calvin Leung	08/16/2010		
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>STMicroelectronics Asia Pacific PTE Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>5A Serangoon North Avenue 5</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>554574</td> </tr> </table>		Name:	STMicroelectronics Asia Pacific PTE Ltd.	Street Address:	5A Serangoon North Avenue 5	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	554574
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CORRESPONDENCE DATA											
Fax Number: (206)682-6031 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 206.622.4900 Email: kristines@seedip.com Correspondent Name: Hayley J. Stevens Address Line 1: 701 Fifth Avenue Address Line 2: Suite 5400 Address Line 4: Seattle, WASHINGTON 98104											
ATTORNEY DOCKET NUMBER:	851663.503										
NAME OF SUBMITTER:	Hayley J. Stevens										
Total Attachments: 2 source=503_Assignment#page1.tif											

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PATENT
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ASSIGNMENT

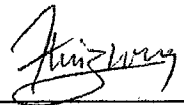
WHEREAS, we, Hui Chong Vince Ng, Olivier Le Néel, and Calvin Leung (hereinafter referred to as ASSIGNORS), having mailing addresses of Blk 26C, Jalan Membina, #25-182, Singapore 166026; 58 Thomson Green, Singapore 574934; and Blk 535, #06-619, Bukit Batok Street 52, Singapore 650535, respectively, are the joint inventors of an invention entitled "LATERAL CONNECTION FOR A VIA-LESS THIN FILM RESISTOR," as described and claimed in the specification for which an application for United States letters patent was filed on August 24, 2010, and assigned Application No. 12/862,589;

WHEREAS, STMicroelectronics Asia Pacific PTE Ltd. (hereinafter referred to as ASSIGNEE), a corporation of Singapore having a place of business at 5A Serangoon North Avenue 5, Singapore 554574, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefor in the United States and in any and all foreign countries;

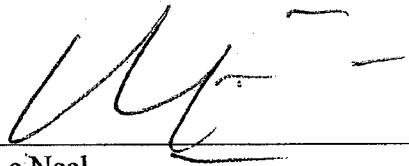
NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto said ASSIGNEE, the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

Assignee's counsel is authorized to insert the official filing date and application number information when it becomes available.

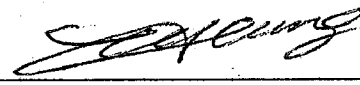
16/08/2010
Date


Hui Chong Vince Ng

16/08/2010
Date


Olivier Le Neel

16/08/2010
Date


Calvin Leung

503 Assignment.DOC
(09-AMK-191/851663.503)